

Abstract

Apparatus for singulating and bonding semiconductor chips, and method for singulating and bonding

The invention relates to an apparatus for singulating and bonding semiconductor chips (1). For this purpose, the apparatus includes a singulating station (2) and a mounting station (11). In the singulating station (2), a semiconductor chip (1) is provided with a bonding wire (5) by a bonding tool (4) and lifted off a carrier film (7). Then, in the mounting station (11), the semiconductor chip (1) is placed on a chip mounting surface (13) and fixed in place there, and the bonding wire (5) is guided to a contact-connection surface (15) of the circuit carrier (12) and bonded to this surface.

[Figure 1]



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